

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently amended) Method for selectively transferring ~~at least one element (12)~~ components from a donor substrate (10) to a target substrate (40), said donor substrate comprising an assembly of components, the element to be transferred being made integral with a handle substrate (30) through the intermediary of a layer of glue (32) whose adherence can be degraded, a degradation of the layer of glue (32) being carried out so as to free the element to be transferred (12), characterised in that it comprises the method comprising the following successive steps:

a) gluing of the ~~element to be transferred (12)~~ assembly of components from the donor substrate (10) onto the ~~a handle support (30)~~ substrate by the intermediary of ~~the a glue layer (32),~~

b) thinning of the donor substrate (10) to provide a layer comprising the assembly of components,

c) degradation of the adherence of the glue layer (32) gluing a sub-assembly of components to be transferred,

d) displacement of the ~~element~~ components to be transferred (12) onto the target substrate (40),

e) separation of the ~~element~~ components to be transferred and the handle substrate; repeating steps c), d) and e) to transfer other subassemblies of components.

2. (Original) Method according to claim 1, wherein a glue used is chosen from among an epoxy glue, a glue to be hardened by ultraviolet radiation, a polymer base glue, or a glue with a wax base.

3. (Previously presented) Method according to claim 1, wherein degradation of the glue layer is carried out by submitting it to a chemical treatment, a heat treatment, a radiation treatment or a plasma treatment or a combination of said treatments.

4-5. (Canceled)

6. (Currently amended) Method according to claim 1, wherein a the handle substrate (~~30~~) is ~~used with~~ comprises access paths (~~34~~) towards a face of the handle substrate able to be put into contact with the layer of glue.

7. (Canceled)

8. (Currently amended) Method according to claim 1, wherein the ~~detachment~~ separation step includes applying traction, pressure, shearing, peeling or bending forces, or any combination of these forces.

9. (Currently amended) Method according to claim 8, wherein the ~~detachment~~ separation step further includes applying a jet of fluid.

10. (Currently amended) Method according to claim 8, wherein the ~~detachment~~ separation step further includes the insertion of a tapered object.

11. (Currently amended) Method according to claim 1 wherein said step of degradation of the adherence of the glue layer (~~32~~) is carried out before said step of displacement of the ~~element~~ components to be transferred (~~12~~) onto the target substrate (~~40~~).

12. (Currently amended) Method according to claim 1 wherein said step of degradation of the adherence of the glue layer (~~32~~) causes a modification of the mechanical hold compatible with ulterior separation.

13. (New) Method according to claim 1, comprising a step of cutting out the layer comprising the assembly of components by making grooves to individualize the components.